**MECHANICAL CASE OUTLINE**

**PACKAGE DIMENSIONS**

**UQFN20 3x4, 0.5P**

**CASE 523BA**

**ISSUE O**

**DATE 31 OCT 2016**

---

**TOP VIEW**

**SIDE VIEW**

**RECOMMENDED LAND PATTERN**

**NOTES:**

A. PACKAGE CONFORMS TO JEDEC MO-220 EXCEPT WHERE NOTED.

B. DIMENSIONS ARE IN MILLIMETERS.


D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

---

**DOCUMENT NUMBER:** 98AON13702G

**STATUS:** ON SEMICONDUCTOR STANDARD

**NEW STANDARD:**

**DESCRIPTION:** UQFN20 3x4, 0.5P

Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

**PAGE 1 OF 2**
<table>
<thead>
<tr>
<th>ISSUE</th>
<th>REVISION</th>
<th>DATE</th>
</tr>
</thead>
<tbody>
<tr>
<td>O</td>
<td>RELEASED FOR PRODUCTION FROM FAIRCHILD UMLP20A TO ON SEMICONDUCTOR. REQ. BY C. TAN.</td>
<td>31 OCT 2016</td>
</tr>
</tbody>
</table>